



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAK® 1212-8 SOLDER PROCESS					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
HAST	164	16 400	130 °C, 85 % RH	0	0
Pressure Pot	246	23 616	121°, 15 PSIG	0	0
Solder DUNK	220	660	260 °C, 10 s	0	0
Temp. Cycle	328	327 500	-55 °C to 150 °C	0	0